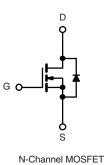


# IRFR3412PBF-VB Datasheet N-Channel 100-V (D-S) MOSFET

PRODUCT SUMMARY				
V <sub>DS</sub> (V)	<b>R<sub>DS(on)</sub> (</b> Ω <b>)</b>	I <sub>D</sub> (A) <sup>a</sup>	Q <sub>g</sub> (Typ.)	
100	0.0185 at V <sub>GS</sub> = 10 V	45	38 nC	

# G D S Top View

TO-252



#### FEATURES

- TrenchFET<sup>®</sup> Power MOSFET
- 100 %  $\rm R_g$  and UIS Tested

#### **APPLICATIONS**

- Primary Side Switch
- Isolated DC/DC Converter



ABSOLUTE MAXIMUM RATING	<b>S</b> (T <sub>A</sub> = 25 °C, unle	ess otherwise i	noted)		
Parameter	Symbol	Limit	Unit		
Drain-Source Voltage		V <sub>DS</sub>	100	v	
Gate-Source Voltage		V <sub>GS</sub>	± 20	v	
	T <sub>C</sub> = 25 °C		45 <sup>a</sup>		
Continuous Drain Current (T $= 150$ °C)	T <sub>C</sub> = 100 °C	I <sub>D</sub>	30		
Continuous Drain Current ( $T_J = 150 \ ^{\circ}C$ )	T <sub>A</sub> = 25 °C		9.2 <sup>b</sup>		
	T <sub>A</sub> = 100 °C		6.8 <sup>b</sup>		
Pulsed Drain Current		I <sub>DM</sub>	140	A	
Continuous Source Drain Diada Current	T <sub>C</sub> = 25 °C	25 °C	45 <sup>a</sup>		
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	۱ <sub>S</sub>	2 <sup>b</sup>		
Single Pulse Avalanche Current	L = 0.1 mH	I <sub>AS</sub>	35		
Avalanche Energy		E <sub>AS</sub>	101	mJ	
	T <sub>C</sub> = 25 °C	-	136.4	W	
Maximum Power Dissipation	T <sub>C</sub> = 100 °C		68.2		
	T <sub>A</sub> = 25 °C	PD	3 <sup>b</sup>	vv	
	T <sub>A</sub> = 100 °C		1.5 <sup>b</sup>	1	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient <sup>b</sup>	Steady State	R <sub>thJA</sub>	40	50	°C/W
Maximum Junction-to-Case	Sleady State	R <sub>thJC</sub>	0.85	1.1	0/11

Notes:

a. Package limited.

b. Surface mounted on 1" x 1" FR4 board.

<b>SPECIFICATIONS</b> ( $T_J = 25^{\circ}$		,		1 _		
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static				1		i
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, \text{ I}_{D} = 250 \mu\text{A}$	100			V
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I <sub>D</sub> = 250 μA		110		mV/°C
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	- <u> </u>		- 12.5		
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	2.5		5	V
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA
Zara Gata Valtaga Drain Current	I <sub>DSS</sub>	$V_{DS} = 100 \text{ V}, V_{GS} = 0 \text{ V}$	1		1	
Zero Gate Voltage Drain Current		$V_{DS}$ = 100 V, $V_{GS}$ = 0 V, $T_{J}$ = 125 $^{\circ}\text{C}$			50	μΑ
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 5 \text{ V}, \text{ V}_{GS} = 10 \text{ V}$	30			A
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 15 A		0.0185		Ω
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 15 A		33		S
Dynamic <sup>b</sup>						
Input Capacitance	C <sub>iss</sub>			2400		pF
Output Capacitance	C <sub>oss</sub>	$V_{DS} = 50 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		230		
Reverse Transfer Capacitance	C <sub>rss</sub>			80		
Total Gate Charge	Qg			38	70	nC
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS} = 50 \text{ V}, \text{ V}_{GS} = 10 \text{ V}, \text{ I}_{D} = 50 \text{ A}$		14		
Gate-Drain Charge	Q <sub>gd</sub>			12		
Gate Resistance	R <sub>g</sub>	f = 1 MHz		1.6	2.5	Ω
Turn-On Delay Time	t <sub>d(on)</sub>			12	20	
Rise Time	t <sub>r</sub>	$V_{DD} = 50 \text{ V}, \text{ R}_{\text{I}} = 1 \Omega$		10	20	ns
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 50$ Å, $V_{GEN} = 10$ V, $R_g = 1 \Omega$		18	35	
Fall Time	t <sub>f</sub>			8	15	
Drain-Source Body Diode Characteris	stics					
Continuous Source-Drain Diode	ا <sub>S</sub>	T <sub>C</sub> = 25 °C			35	A
Pulse Diode Forward Current <sup>a</sup>	I <sub>SM</sub>	Ŭ			100	
Body Diode Voltage	V <sub>SD</sub>	I <sub>S</sub> = 15 A		0.85	1.5	V
Body Diode Reverse Recovery Time	t <sub>rr</sub>			80	120	ns
Body Diode Reverse Recovery Charge Q <sub>rr</sub>				160	240	nC
Reverse Recovery Fall Time	t <sub>a</sub>	l <sub>F</sub> = 50 A, dl/dt = 100 A/μs, T <sub>J</sub> = 25 °C		57		
Reverse Recovery Rise Time				23		ns

Notes:

a. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.

b. Guaranteed by design, not subject to production testing.

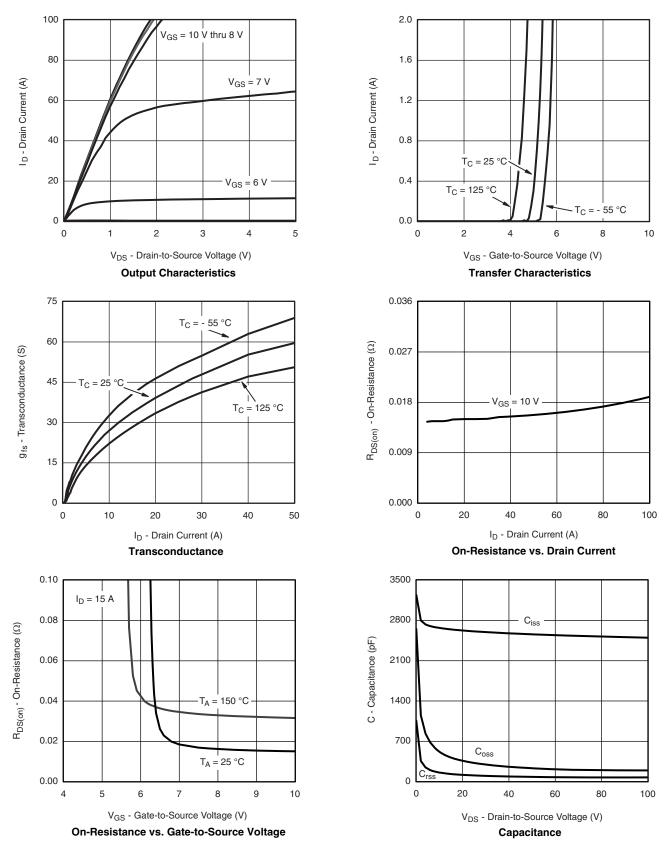
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

**Bsemi** 

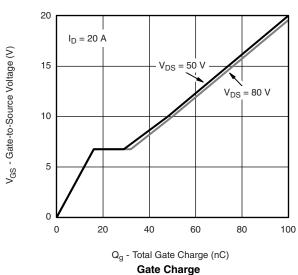
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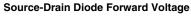
#### TYPICAL CHARACTERISTICS (25 °C, unless otherwise note)

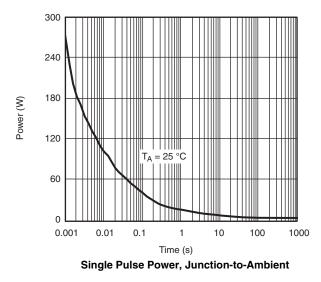


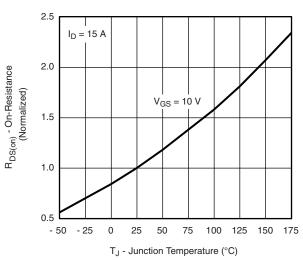




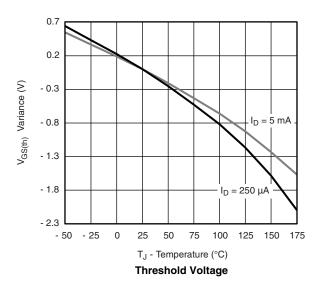
#### 100 T<sub>J</sub> = 150 °C 10 I<sub>S</sub> - Source Current (A) T<sub>J</sub> = 25 °C 1 0.1 0.01 0.001 0.0 0.2 0.4 0.6 0.8 1.0 1.2 V<sub>SD</sub> - Source-to-Drain Voltage (V)

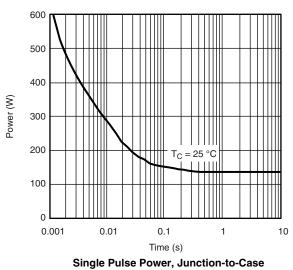






**On-Resistance vs. Junction Temperature** 

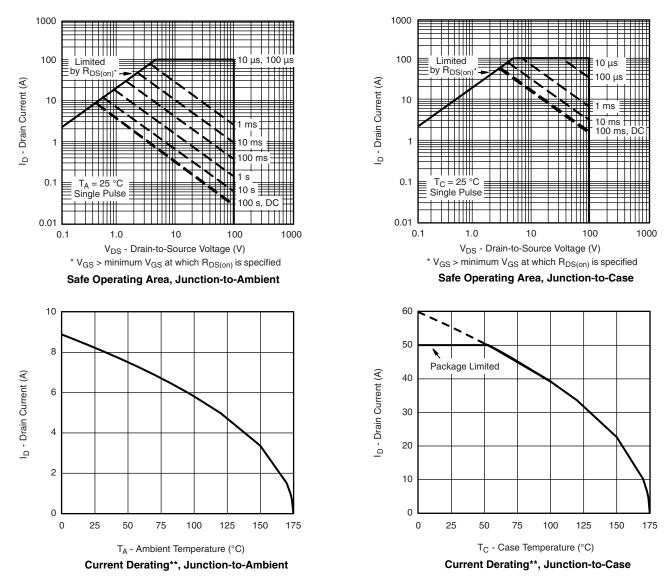




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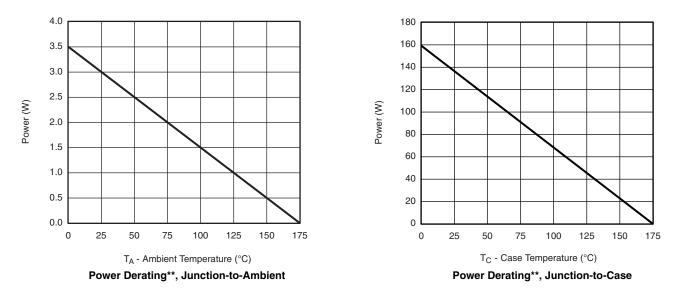


#### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



\*\* The power dissipation  $P_D$  is based on  $T_{J(max.)} = 175$  °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



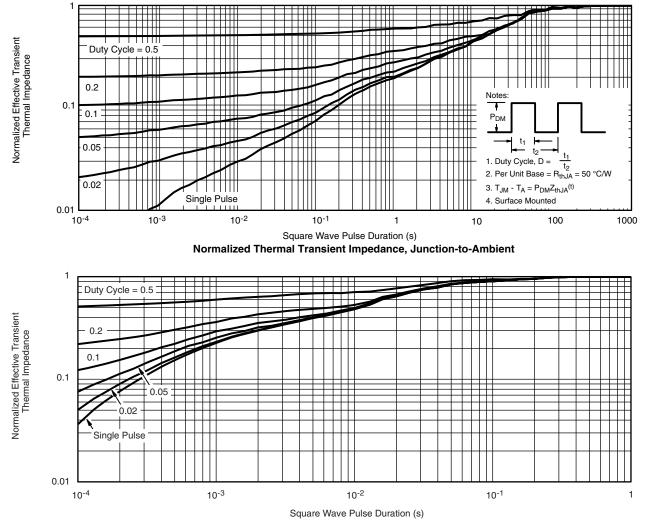


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\*\* The power dissipation  $P_D$  is based on  $T_{J(max)} = 175$  °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



#### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case



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